("4910642").PN.  Cooling and (expandable adj USPAT 15:16  Cooling and (bellow\$!) and semiconductor  Cooling and (bellow\$!) and cooling and (bellow\$!) and semiconductor  Cooling and (bellow\$!) and chip\$!  Cooling and (bellow\$! same (beat ajd sin\$!)) and chip\$!  Cooling and (bellow\$! same (bellow\$! same (beat ajd pipe\$!)) and chip\$!  Cooling and (bellow\$! same (bellow\$! same (beat ajd pipe\$!)) and chip\$!  Cooling and (bellow\$! same (bellow\$! same (beat ajd pipe\$!)) and chip\$!  Cooling and (bellow\$! same (bellow\$! same (beat ajd pipe\$!)) and chip\$!  Cooling and (bellow\$! same (bellow\$! adj pipe\$!)) and chip\$!  Cooling and (bellow\$! same (bellow\$! adj pipe\$!)) and chip\$!  Cooling and (bellow\$! same (bellow\$! adj pipe\$!)) and chip\$!  Cooling and (bellow\$! adj pipe\$!)) and chip\$!	Type		Hits	Search Text	DBs	Time Stamp	Comments	Error
dable adj USPAT  ow\$1) and USPAT  ow\$1 same	IS&R 1	Н		•	USPAT	2004/07/08 15:16		TOTA THE TOTAL
cooling and (bellow\$1) and (beat ajd sink\$1)) and (beat ajd sink\$1)) and (beat ajd sink\$1)) and chip\$1 Semiconductor  cooling and (bellow\$1 Same (beat ajd sink\$1)) and chip\$1 DERWENT; IBM_TDB (cooling and (bellow\$1 Same (heat ajd sink\$1)) and chip\$1 DERWENT; IBM_TDB (cooling and (bellow\$1 Same (heat ajd sink\$1)) and chip\$1 BERWENT; IBM_TDB (cooling and (bellow\$1 Same (heat ajd sink\$1)) and chip\$1 BERWENT; IBM_TDB (cooling and (bellow\$1 Same (heat ajd sink\$1)) and chip\$1 BERWENT; IBM_TDB (semiconductor\$1 or chip\$1) and (bellow\$1 Same (heat ajd pipe\$1)) BERWENT; IBM_TDB (cooling and (bellow\$1 adj DERWENT; IBM_TDB (cooling an	BRS 1	н		and (expandable and semiconducto	USPAT	2004/07/08 15:16		
ow\$1 same  uSPAT  ow\$1 same  EPO; JPO;  and chip\$1 DERWENT; IBM_TDB  low\$1 same  and chip\$1 DERWENT; IBM_TDB  low\$1 same  bellow\$1  c\$1) and  Cchip\$1)  Cchip\$1)  DERWENT; EPO; JPO;  and  DERWENT; EPO; JPO;  and  DERWENT; EPO; JPO;  and  Cchip\$1)  DERWENT; IBM_TDB  ow\$1 same  USPAT; EPO; JPO;  and  DERWENT; IBM_TDB  cchip\$1)  DERWENT; IBM_TDB  ow\$1 same  USPAT; EPO; JPO;  and  DERWENT; IBM_TDB  ow\$1 adj  USPAT; EPO; JPO;	BRS 1232	1232		( bellow or	USPAT	2004/07/08 15:17		***************************************
ow\$1 same and chip\$1 low\$1 same and chip\$1 bellow\$1 same and chip\$1 c\$1) and chip\$1 c\$1) and chip\$1) ow\$1 same and chip\$1) ow\$1 same and chip\$1) ow\$1 same chip\$1) ow\$1 same and chip\$1) ow\$1 adj	BRS 285	285		(bellow\$1 ink\$1) and or		2004/07/08 15:34		
ow\$1 same and chip\$1 low\$1 same and chip\$1) bellow\$1 same \$\(\delta \) and \$\(\delta \) ow\$1 same and \$\(\delta \) chip\$1) \$\(\delta \) and \$\(\delta \) ow\$1 same \$\(\delta \) and \$\(\delta \) ow\$1 same \$\(\delta \) ow\$1 same \$\(\delta \) ow\$1 same \$\(\delta \) ow\$1 adj \$\(\delta \)	BRS 66	99		ow\$1 and	EPO; JPO; DERWENT; IBM_TDB	2004/07/09 08:50		
low\$1 same and chip\$1) bellow\$1 c\$1)) and  bellow\$1 chip\$1) chip\$1) berwent; chip\$1) chip\$2) chip\$2	BRS 54	54	***************************************	cooling and (bellow\$1 same (heat ajd sink\$1)) and chip\$1	EPO; JPO; DERWENT; IBM_TDB	2004/07/08 15:46		
and (bellow\$1 same jd pipe\$1) and nductor\$1 or chip\$1) and (bellow\$1 same jd pipe\$1) and nductor\$1 or chip\$1) and (bellow\$1 adj and (bellow\$1 adj	BRS 27	27		low\$1 same and chip\$1) bellow\$1 <\$1)) and	• •	2004/07/08 15:46		
and ( bellow\$1 same jd pipe\$1)) and nductor\$1 or chip\$1) and ( bellow\$1 adj jd pipe\$1))	BRS 554	554	134 (81-4)	and ( bellow\$1 same jd pipe\$1)) and nductor\$1 or chip\$1)	USPAT; EPO; JPO; ; DERWENT; IBM_TDB	2004/07/09 08:51		
and ( bellow\$1 adj jd pipe\$1))	BRS 554	554		and ( bellow\$1 same jd pipe\$1)) and nductor\$1 or chip\$1)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 39:54		
	BRS 121	121		and ( bellow\$1 adj jd pipe\$1))	USPAT; EPO; JPO; 2	2004/07/09 09:54		

	Туре	#	Hits	Search Text	DBs	Time Stamp	Comment	Error Definition	H O I
Н	IS&R	디		("4910642").PN.	USPA	2004/07/0 8 15:16			a 0
7	BRS	L2	Н	cooling and (expandable adj bellow) and semiconductor	USPA	2004/07/0 8 15:16			0
м	BRS	L3	1232	cooling and (bellow\$1) and semiconductor	USPA	2004/07/0 8 15:17			0
4,	BRS	L4	285	cooling and (bellow\$1 same (heat ajd sink\$1) and semiconductor	USPA T	2004/07/0 8 15:34			0
ഗ	BRS	L.5	99	cooling and ( bellow\$1 same (heat ajd sink\$1)) and semiconductor	EPO; JPO; DERW ENT; IBM TDB	2004/07/0 8 15:46			0
ω	BRS	L6	4.2	cooling and ( bellow\$1 same (heat ajd sink\$1)) and chip\$1	EPO; JPO; DERW; ENT; IBM TDB	2004/07/0 8 15:46			0
7	BRS	1.7	27	6 not 5	EPO; JPO; DERW ENT; IBM TDB	2004/07/0 8 15:46			0